

Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

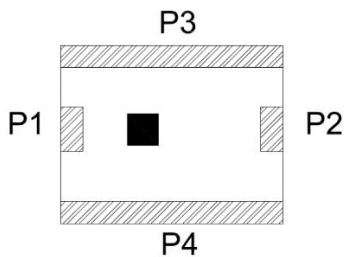
Specifications

NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	5725~5850			2.3
2	VSWR				2.0
3	Ripple (dB)				1
4	Attenuation (dB)	902~928	50		
		3919~4044	30		
		4822~4947	30		
5	In/Output Impedance (Ω)		50		
6	Permissible Input Power (W)				1

Operating & Storage Condition (Component)
 Operation Temperature Range: -40°C ~ +85°C
 Storage Temperature Range: -40°C ~ +85°C

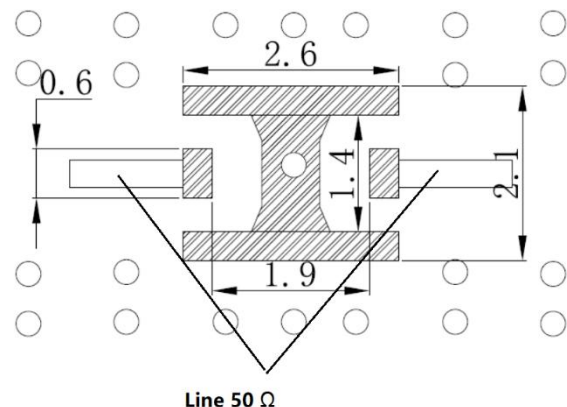
Storage Condition before Soldering (Included packaging material)
 Storage Temperature Range: +5 ~ +40 °C
 Humidity: 30 to 70% relative humidity

Construction



PIN	Connection	PIN	Connection
1	Input port	3	GND
2	Output port	4	GND

Mounting Considerations



Unit: mm

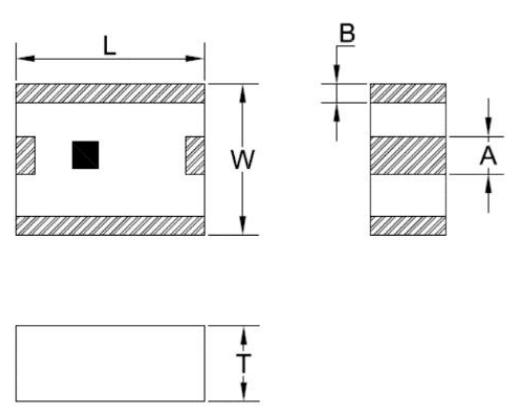
Yantel Corporation

Add: No.308-322,3F,Building 1,Juchuang Jingu Innovation Park,Wenyuan Road 35,Xili Street,Nanshan,Shenzhen,China

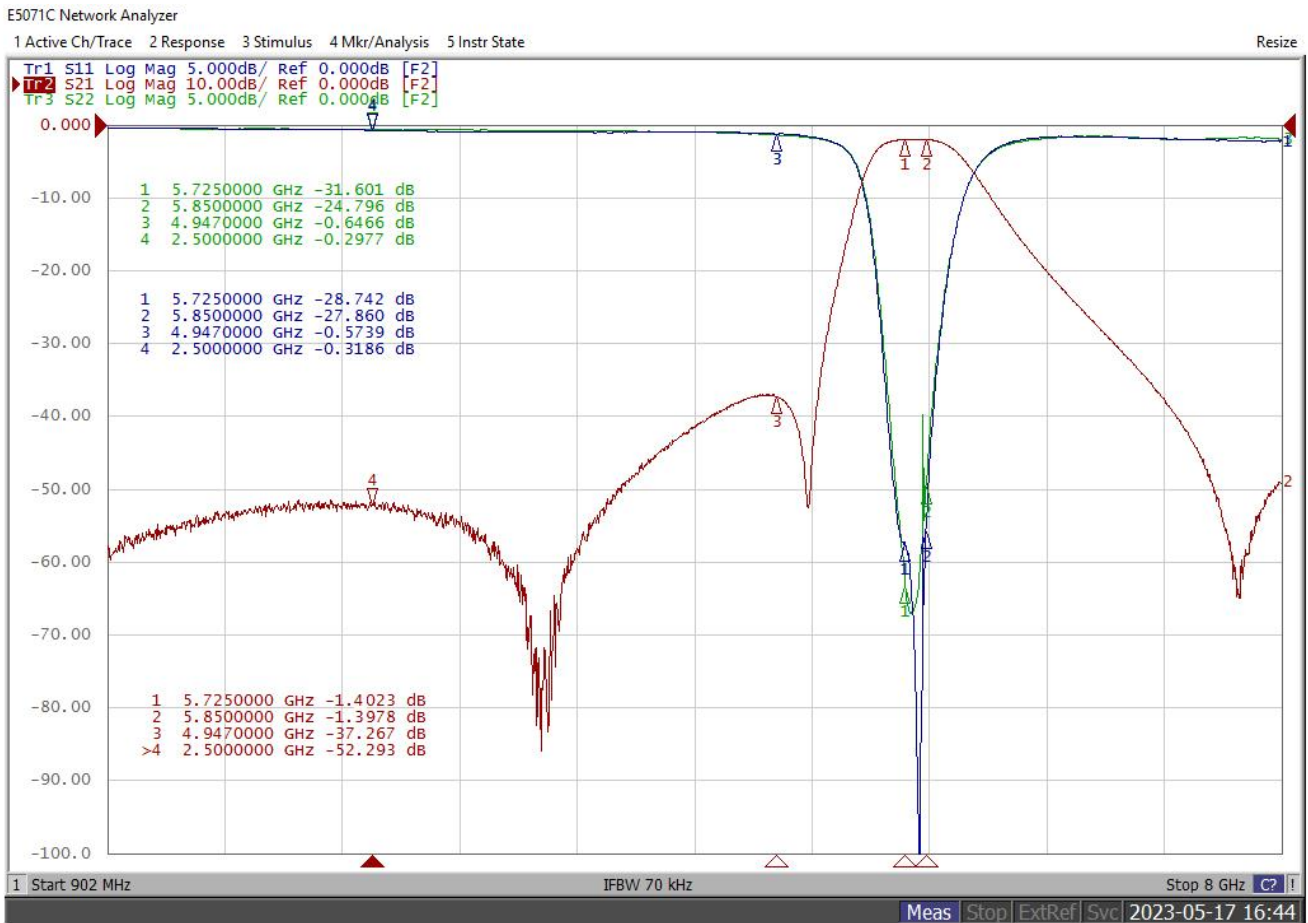
Tel: 86-755-8355-1886 Fax: 86-755-8355-2533

For detailed performance specs & shopping online see Yantel web site : www.yantel-corp.com

Dimensions

Figure	Symbol	Dimension (mm)
	L	2.50±0.20
	W	2.0±0.20
	T	1.0±0.20
	A	0.50±0.10
	B	0.20±0.10

Typical Electrical Characteristics (T=25° C)



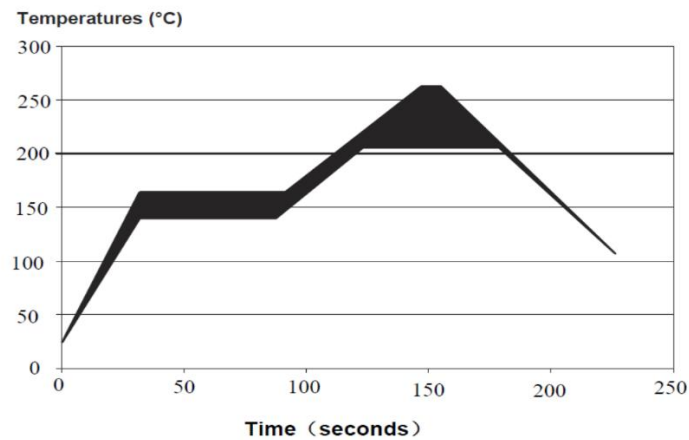
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Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.